

ABSTRACT OF THE DISCLOSURE
METHOD AND APPARATUS FOR ADHERING ELECTRONIC
COMPONENTS

A method for adhering two electronic components
5 includes: placing a plurality of first electronic
components on a carrier tray in a matrix arrangement;
releasably packaging a plurality of second electronic
components in a carrier tape assembly having a carrier
tape and a cover tape peelably adhered to the carrier
10 tape; picking up and transferring one of the first
electronic components to a fixture by a first transfer
mechanism; and picking up and transferring one of the
second electronic components to the fixture by a second
transfer mechanism so as to adhere the one of the second
15 electronic components to the one of the first
electronic components and form an assembly.

Fig. 4